

On page 22, please replace the abstract with the following new abstract:

A probe card covering system includes a probe card for testing a die on a wafer, the probe card having contacts adapted for electrical engagement with the die; a removable cover connected to the probe card and positionable in a first position over the contacts of the probe card, the cover being movable to a second position exposing said contacts for the engagement with the die; and, wherein the cover is movable from the first position to the second position while the probe card is located in a wafer testing machine.